

Please add new claim 8 as follows:

- 8. (NEW) A semiconductor device comprising:  
a substrate;  
a semiconductor chip having one surface bonded to a surface of the substrate; and  
a warp preventing sheet bonded to the other surface of the semiconductor chip, wherein  
the substrate and the warp preventing sheet are fabricated from different materials and a substrate thickness of the substrate and a warp preventing sheet thickness of the warp preventing sheet are different from each other yet respective ones of at least one of the coefficients of elasticity and coefficients of thermal expansion are equal to each other.--

### **REMARKS**

Claims 1-8 are pending in the application. By this Amendment, claim 1 is amended and claim 8 is added.

Claims 1-5 and 7 are rejected under 35 U.S.C. 102(e) as anticipated by Morrell et al. (U.S. Patent No. 5,895,976). The rejection is respectfully traversed.

Morrell discloses a microelectronic assembly that has a substrate 14 and an integrated circuit die 12 flip-chip bonded to the surface of the substrate 14 and a polymeric reinforcement 18. The polymeric reinforcement 18 is disposed on a surface 27 of the integrated circuit die 12, overlying the center region thereof. However, the polymeric reinforcement 18 does not cover the entire region of the surface 27.

Claim 1 is directed to a semiconductor device that includes a substrate, a semiconductor chip having one surface bonded to a surface of the substrate; and a warp preventing sheet. Claim 1 recites that the warp preventing sheet is bonded to and entirely covers the other surface of the semiconductor chip. Furthermore, claim 1 recites that end surfaces of the warp preventing sheet are flush with corresponding end surfaces of the semiconductor chip.

It is respectfully submitted that the rejection is improper because the applied art